CMOS Digital Integrated Circuits Silicon Monolithic

TC7USB42MU

1. Functional Description

- Dual SPDT USB Switch

2. General

The TC7USB42MU is high-speed CMOS dual 1-2 multiplexer/demultiplexer. The low ON-resistance and the low capacitance of the switch allow connections to USB2.0 (480Mbps) application.

This device consists of dual individual two-inputs multiplexer/demultiplexer with common select input (S) and output enable ($\overline{OE}$). The D+/D- inputs is connected to the 1D+/1D- or 2D+/2D- outputs determined by the combination both the select input (S) and output enable ($\overline{OE}$). When the output enable ($\overline{OE}$) input is held high level, the switches are open with regardless the state of select inputs and a high-impedance state exists between the switches.

All inputs are equipped with protection circuits against static discharge.

3. Features

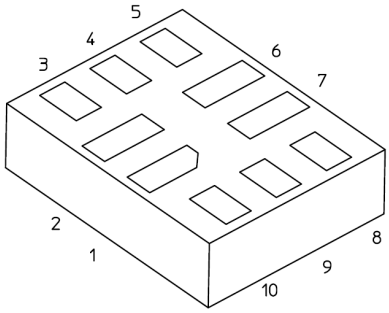
(1) Supply voltage: V_{CC} = 2.3 to 4.3 V
(2) Switch terminal ON-capacitance: $C_{I/O}$ = 5 pF Switch ON (typ.) @V_{CC} = 3.3 V
(3) ON-resistance: R_{ON} = 4.5 Ω (typ.) @V_{CC} = 3 V, V_{IS} = 0 V
(4) R_{ON} flatness: $R_{ON(flat)}$ = 1.3 Ω (typ.)@V_{CC} = 3 V
(5) Difference of ON-resistance between switches: ΔR_{ON} = 0.35 Ω (typ.)@V_{CC} = 3 V
(6) Power-down protection provided on all inputs and outputs.
(7) Ultra-small Package: UQFN10B, UQFN10

Start of commercial production
2020-06

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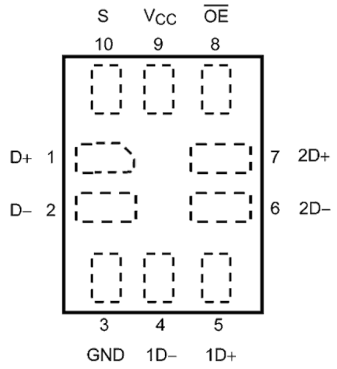
2020-06-16
Rev.4.0

4. Packaging and Pin Assignment (Note)

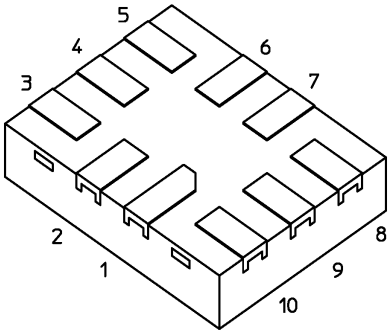


BOTTOM VIEW

UQFN10B

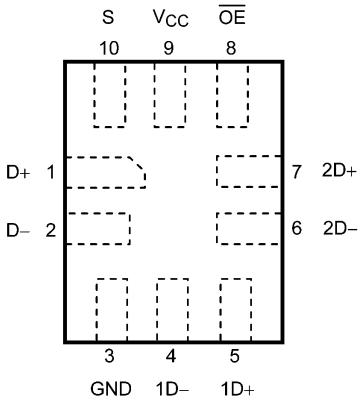


TOP VIEW



BOTTOM VIEW

UQFN10



TOP VIEW

Note: The shapes and dimensions of the package vary, depending on the manufacturing plant. For details, contact the Toshiba sales representative.

5. Marking

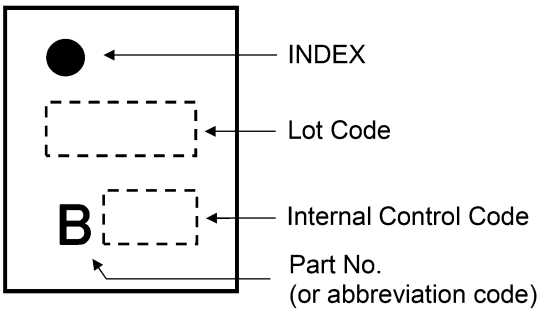


Fig. 5.1 UQFN10B (Top view)

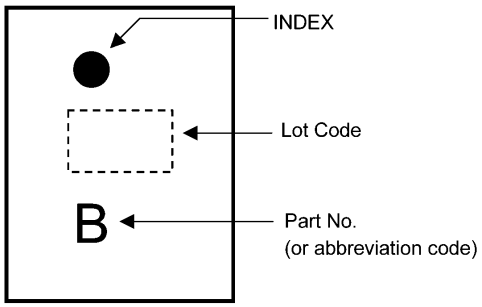


Fig. 5.2 UQFN10 (Top view)

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6. Block Diagram

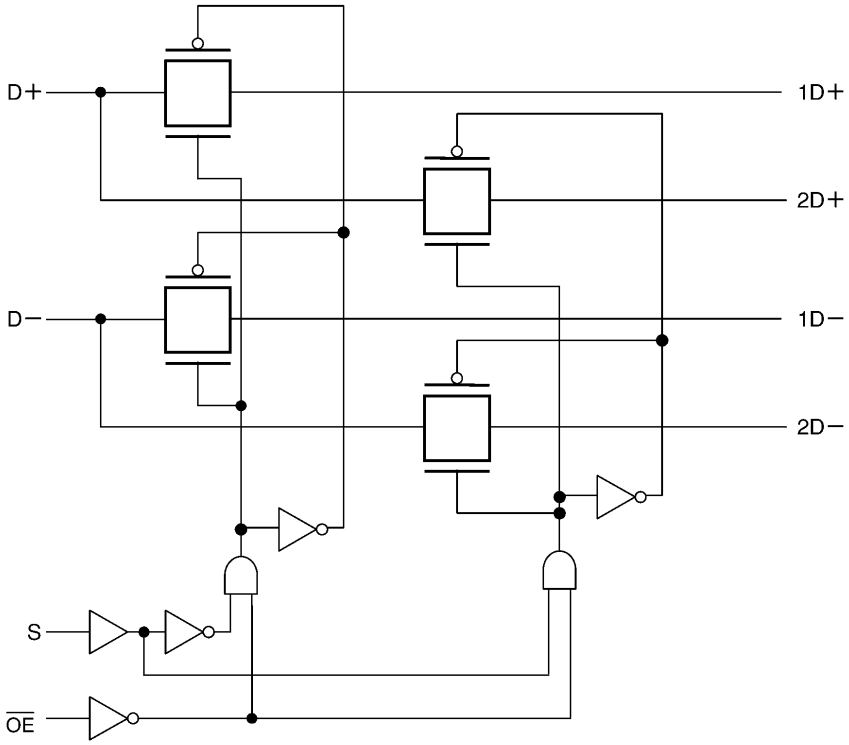


Fig. 6.1 Block Diagram

7. Principle of Operation

7.1. Truth Table

Input $\overline{OE}$	Input S	Function
L	L	D+ port = 1D+ port, D- Port = 1D- Port
L	H	D+ port = 2D+ port, D- Port = 2D- Port
H	X	Disconnect

X: Don't care

8. Absolute Maximum Ratings (Note)

Characteristics	Symbol	Note	Test Condition	Rating	Unit
Supply voltage	V_{CC}		—	-0.5 to 4.6	V
Input voltage ($\overline{OE}$, S)	V_{IN}			-0.5 to 4.6	
Switch I/O voltage	V_S		V_{CC} = 0 V or Switch OFF	-0.5 to 4.6	
			Switch ON	-0.5 to V_{CC} +0.5	
Clamp diode current	I_{IK}		Control input	-50	mA
			Switch	±50	
Switch I/O current	I_S		—	50	
Power dissipation	P_D			200	mW
V_{CC}/ground current	I_{CC}/I_{GND}			±100	mA
Storage temperature	T_{stg}			-65 to 150	°C

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

9. Operating Ranges (Note)

Characteristics	Symbol	Note	Test Condition	Rating	Unit
Supply voltage	V_{CC}		—	2.3 to 4.3	V
Input voltage ($\overline{OE}$, S)	V_{IN}			0 to 4.3	
Switch I/O voltage	V_S		V_{CC} = 0 V or Switch OFF	0 to 4.3	
			Switch ON	0 to V_{CC}	
Operating temperature	T_{opr}		—	-40 to 85	°C
Input rise time	dt/dv			0 to 10	ns/V
Input fall time				0 to 10	

Note: The operating ranges must be maintained to ensure the normal operation of the device.
Unused inputs and bus inputs must be tied to either V_{CC} or GND.

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10. Electrical Characteristics

10.1. DC Characteristics (Note) (Unless otherwise specified, T_a = -40 to 85°C)

Characteristics	Symbol	Note	Test Condition	V_{CC} (V)	Min	Typ.	Max	Unit
High-level input voltage ($\overline{OE}$, S)	V_{IH}		—	2.3 to 3.0	0.50 × V_{CC}	—	—	V
				3.0 to 4.3	0.46 × V_{CC}	—	—	
Low-level input voltage ($\overline{OE}$, S)	V_{IL}		—	2.3 to 4.3	—	—	0.25 × V_{CC}	
Input leakage current ($\overline{OE}$, S)	I_{IN}		V_{IN} = 0 to 4.3 V	2.3 to 4.3	—	—	±1	μA
Power-OFF leakage current	I_{OFF}		V_{IN} = V_{IS} = 0 to 4.3 V, See Fig. 11.10	0	—	—	±2	
Switch OFF-state leakage current	I_{SZ}		V_{IS} = 0 to 3.6 V, $\overline{OE}$ = V_{CC}, See Fig. 11.11	2.3 to 4.3	—	—	±2	
ON-resistance	R_{ON}	(Note 1)	V_{IS} = 0 V, I_{IS} = 30 mA, See Fig. 11.9	3.0	—	4.5	6	Ω
			V_{IS} = 0.4 V, I_{IS} = 30 mA, See Fig. 11.9	3.0	—	4.8	6.7	
			V_{IS} = 3.0 V, I_{IS} = 30 mA, See Fig. 11.9	3.0	—	10	14	
Difference of ON-resistance between switches	ΔR_{ON}	(Note 1)	V_{IS} = 0.4 V, 1.0 V, I_{IS} = 30 mA	3.0	—	0.35	—	
ON-resistance flatness	$R_{ON(flat)}$	(Note 1)	V_{IS} = 0 V to 1.0 V, I_{IS} = 30 mA	3.0	—	1.3	—	
Quiescent supply current	I_{CC}		V_{IN} = V_{CC} or GND, I_{OUT} = 0 A	4.3	—	—	1	μA
	ΔI_{CC}		V_{IN} = 2.6 V (one input)	4.3	—	—	40	

Note: All typical values are at T_a = 25°C.

Note 1: Measured by the voltage drop between D+/D- and 1D+/1D-,2D+/2D- pins at the indicated current through the switch. On-resistance is determined by the lower of the voltages on the two pins.

10.2. AC Characteristics (Note) (Unless otherwise specified, T_a = -40 to 85°C)

Characteristics	Symbol	Note	Test Condition	V_{CC} (V)	Min	Typ.	Max	Unit
Propagation delay time	t_{PLH}/ t_{PHL}	(Note 1)	C_L = 5 pF, See Fig. 11.1	3.3 ± 0.3	—	0.25	—	ns
Turn-ON time (S, $\overline{OE}$ to output)	t_{on}		R_L = 50 Ω, C_L = 5 pF, See Fig. 11.2		—	10	20	
Turn-OFF time (S, $\overline{OE}$ to output)	t_{off}				—	14	24	
Break before make	TBBM		R_L = 50 Ω, C_L = 5 pF, See Fig. 11.3		2	—	7	
Skew of opposite transitions of the same output (t_{PHL} - t_{PLH})	$t_{SK(P)}$	(Note 1)	C_L = 5 pF, See Fig. 11.4		—	0.1	—	
Output skew (center port to any other port)	$t_{SK(O)}$	(Note 1)	C_L = 5 pF, See Fig. 11.5		—	0.1	—	

Note: All typical values are at T_a = 25°C.

Note 1: Parameter guaranteed by design.

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10.3. Analog Switch (Note) (Unless otherwise specified, T_a = -40 to 85°C)

Characteristics	Symbol	Note	Test Condition	V_{CC} (V)	Min	Typ.	Max	Unit
OFF isolation (non-adjacent)	OIRR		R_T = 50 Ω, f = 240 MHz, See Fig. 11.6	3.3 ± 0.3	—	-24	—	dB
Crosstalk (non-adjacent)	Xtalk		R_T = 50 Ω, f = 240 MHz, See Fig. 11.7		—	-30	—	
-3dB Bandwidth	BW		R_T = 50 Ω, C_L = 0 pF, See Fig. 11.8		—	1500	—	MHz

Note: All typical values are at T_a = 25°C.
Parameter guaranteed by design.

10.4. Capacitive Characteristics (Note) (Unless otherwise specified, T_a = 25°C)

Characteristics	Symbol	Note	Test Condition	V_{CC} (V)	Typ.	Unit
Input capacitance ($\overline{OE}$, S)	C_{IN}		V_{IN} = 0 V	3.3	3	pF
Switch terminal OFF-capacitance (D+, D-)	$C_{I/O}$		$\overline{OE}$ = V_{CC}, V_{IS} = 0 V		3	
Switch terminal OFF-capacitance (1D+, 1D-, 2D+, 2D-)					2	
Switch terminal ON-capacitance			$\overline{OE}$ = GND, V_{IS} = 0 V		5	

Note: Parameter guaranteed by design.

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11. AC Test Circuits and Waveforms

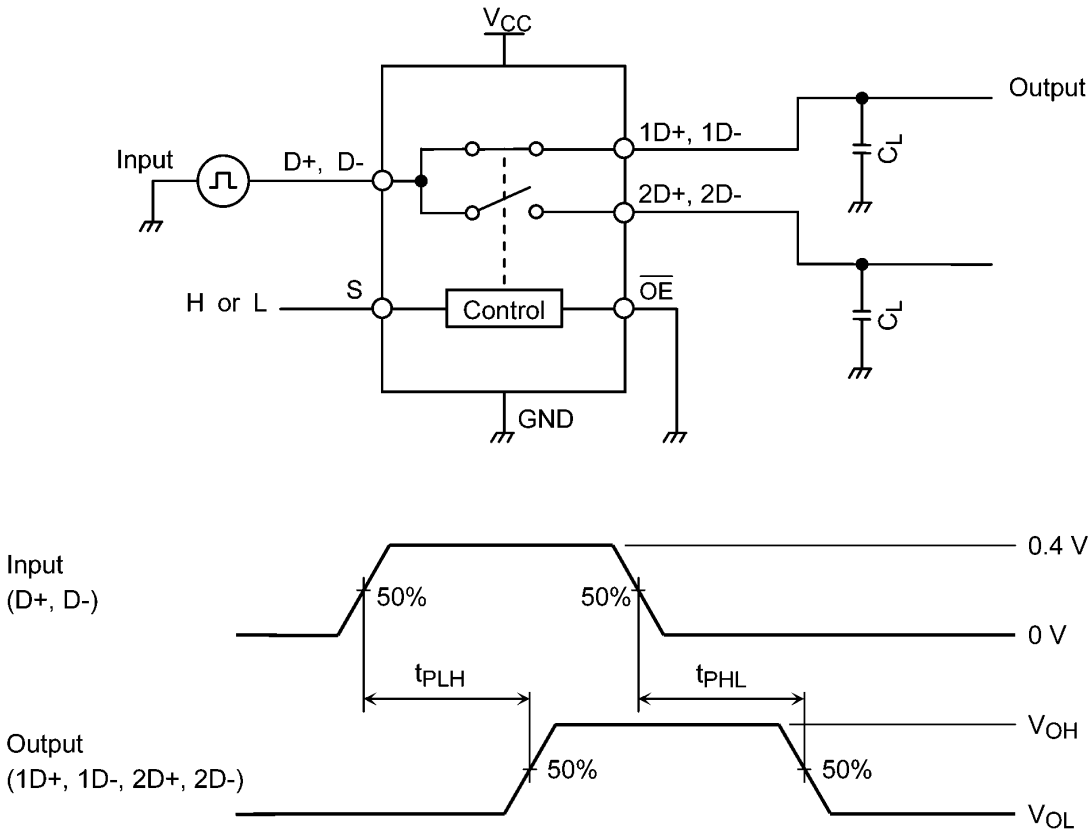


Fig. 11.1 Propagation Delay Time (t_{PLH}, t_{PHL})

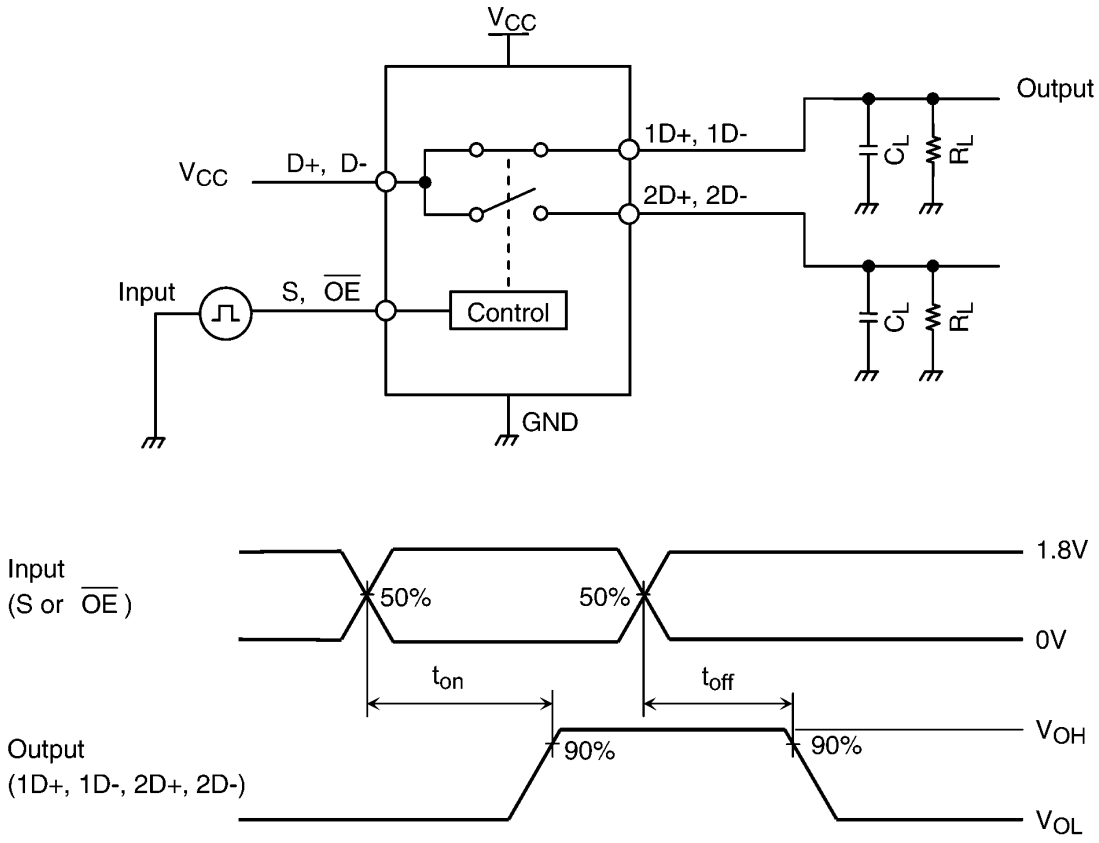


Fig. 11.2 Turn-ON and Turn-OFF Times (t_{on}, t_{off})

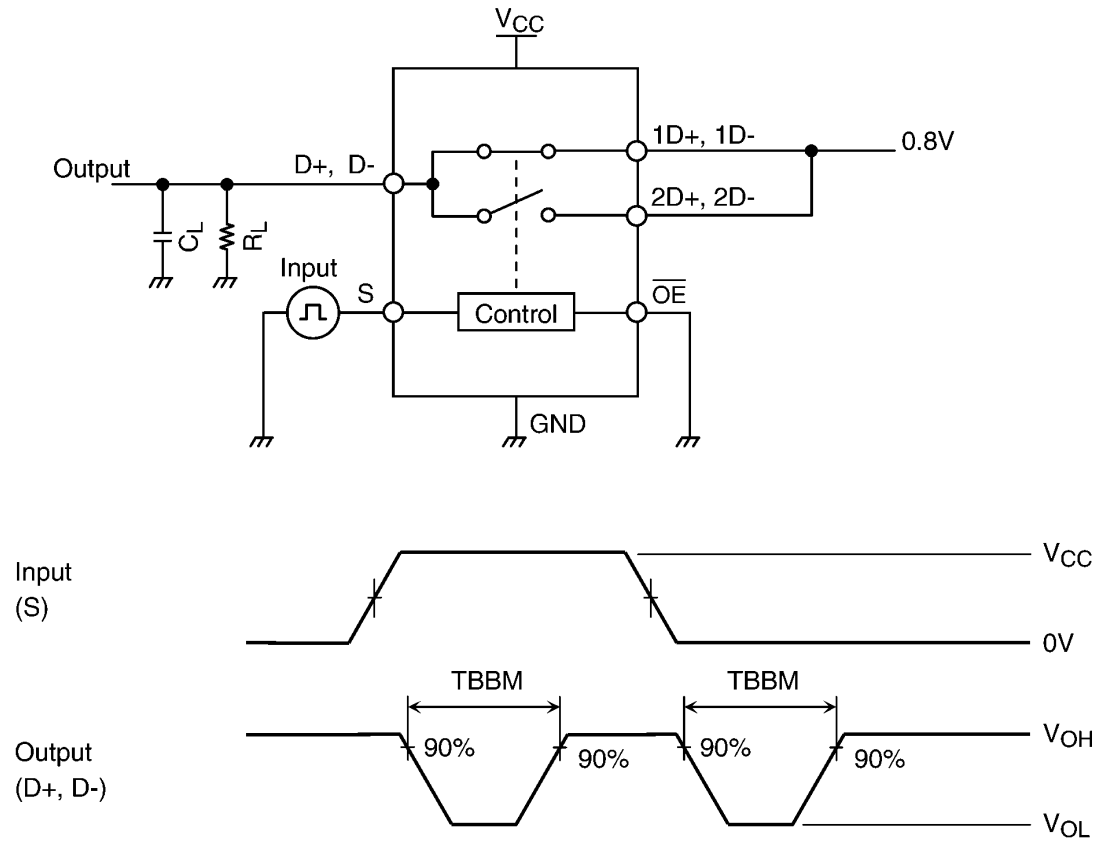


Fig. 11.3 Break Before Make (TBBM)

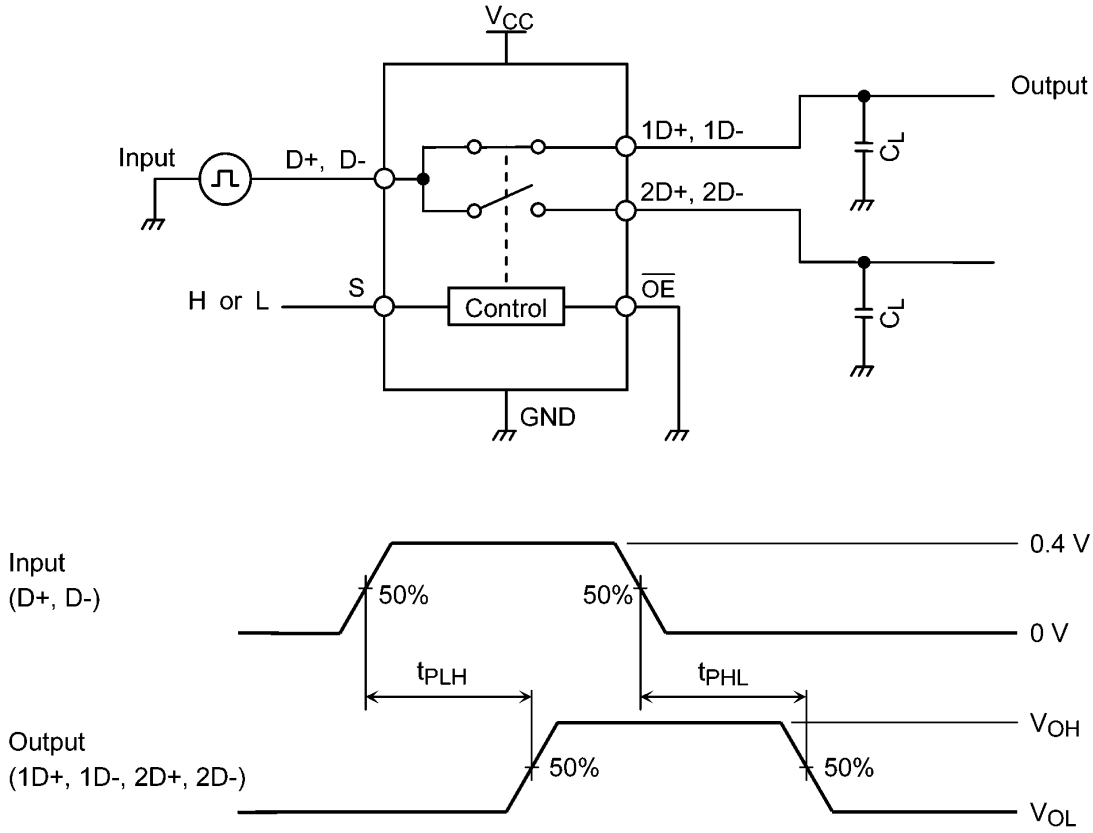


Fig. 11.4 Skew of opposite transitions of the same output ($t_{SK(P)} = |t_{PHL} - t_{PLH}|$)

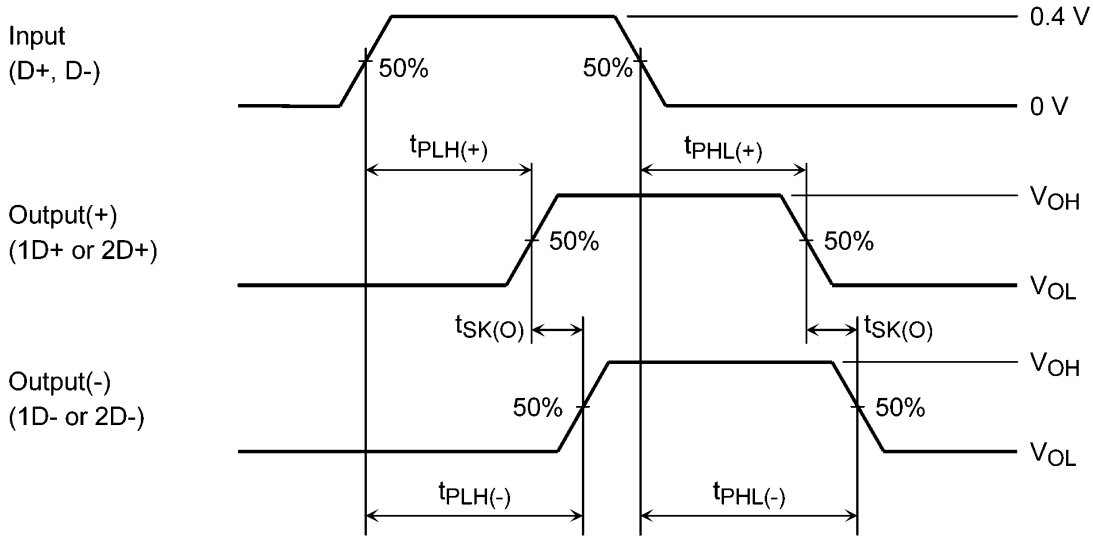


Fig. 11.5 Output Skew (center port to any other port)

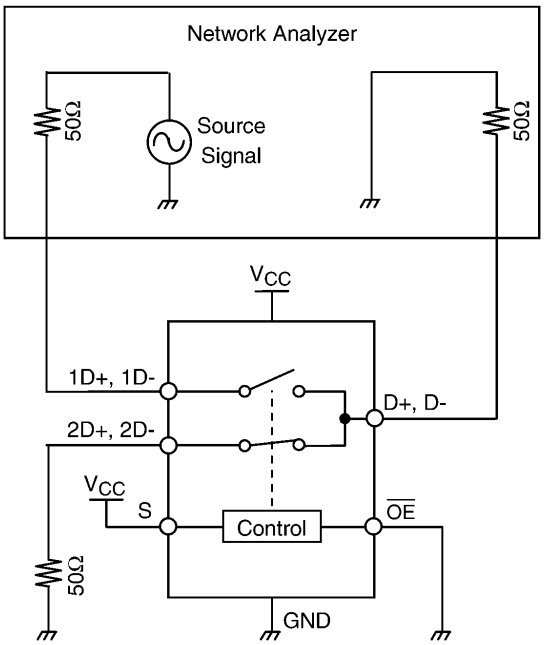


Fig. 11.6 OFF Isolation

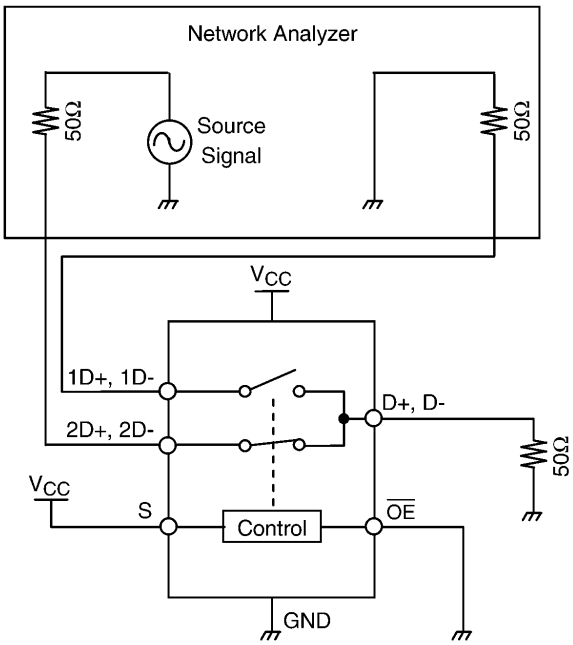


Fig. 11.7 Crosstalk

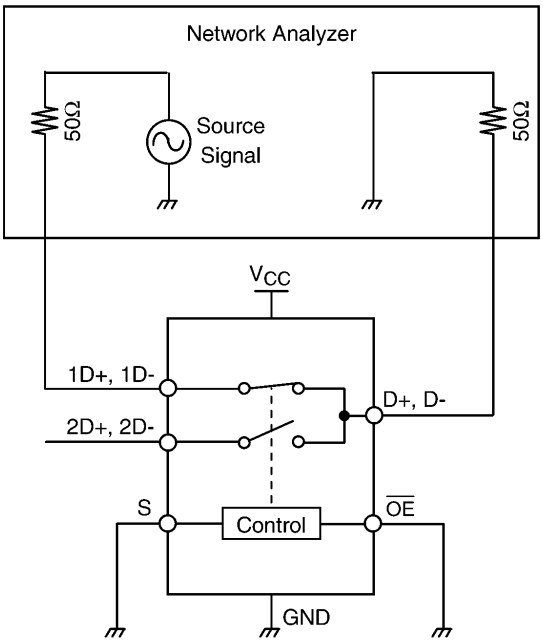


Fig. 11.8 -3dB Bandwidth

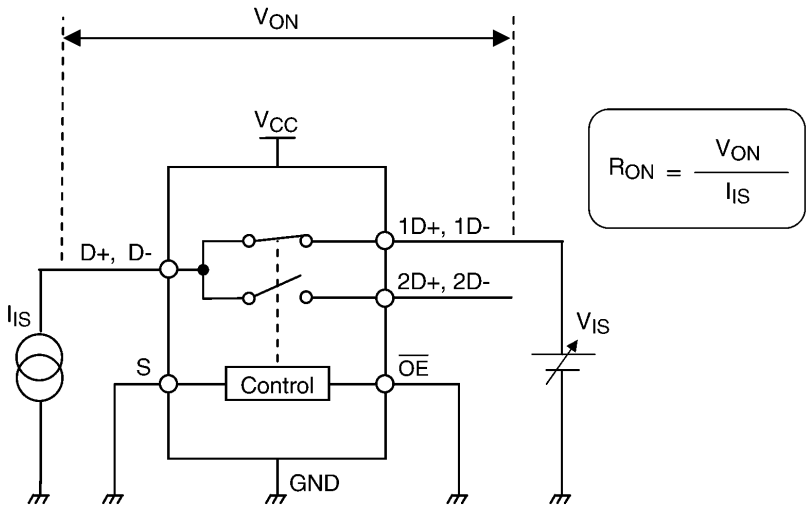


Fig. 11.9 ON-Resistance

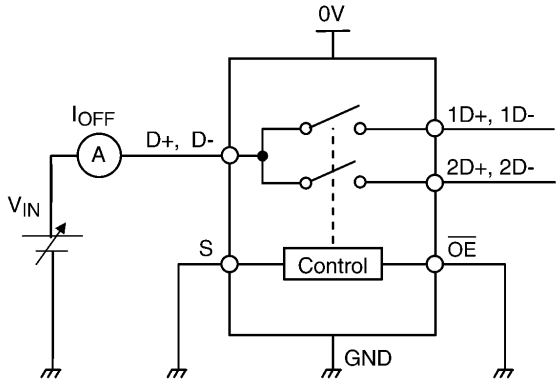


Fig. 11.10 Power-OFF Leakage Current

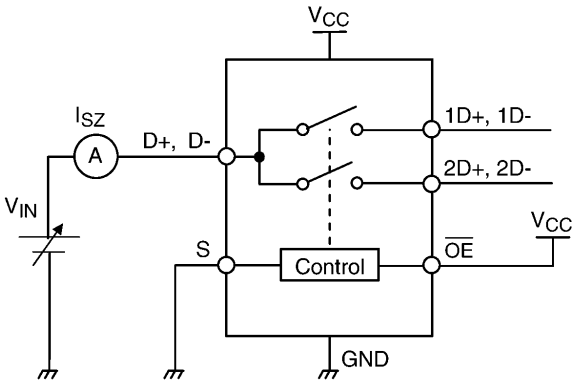
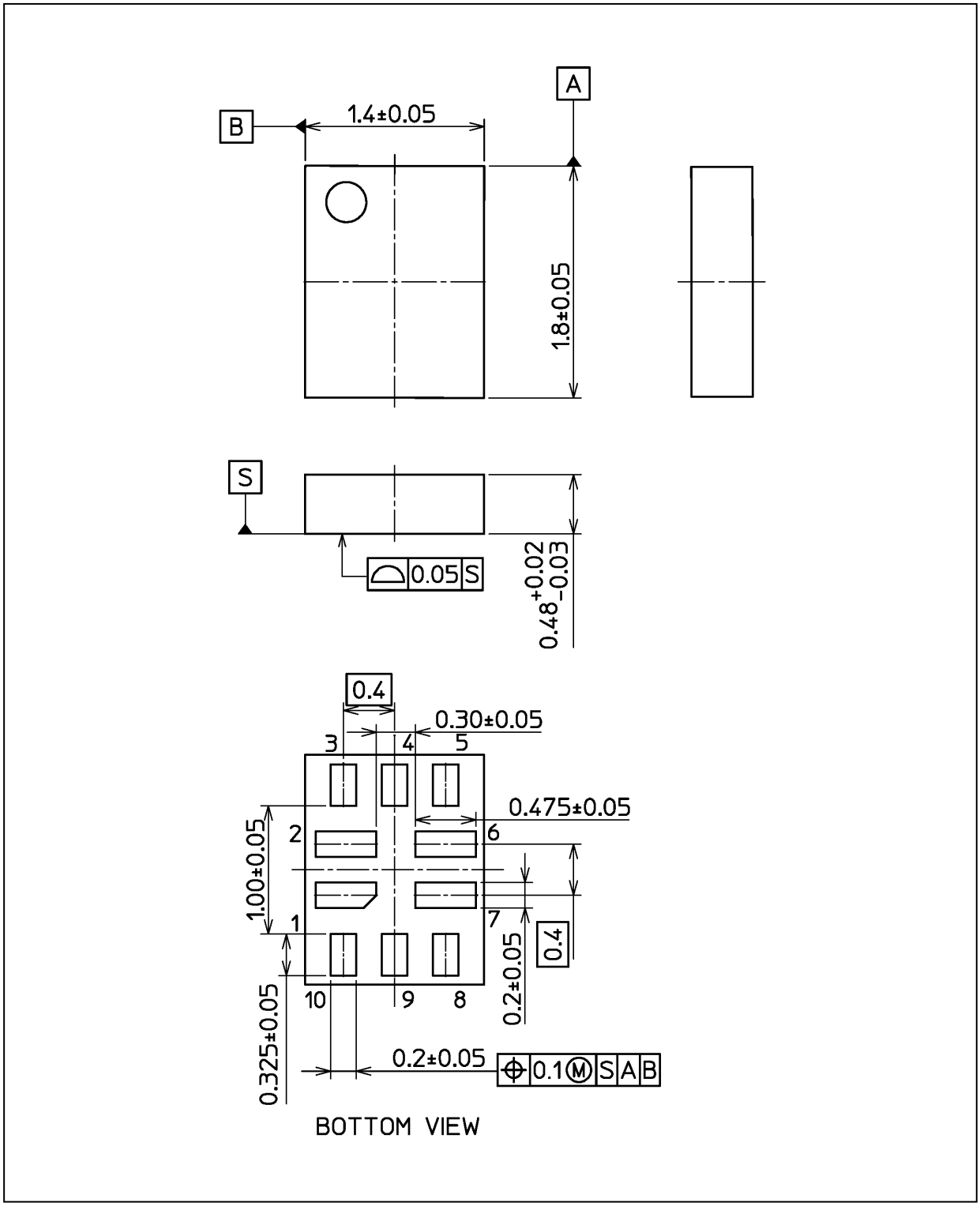


Fig. 11.11 Switch OFF-state leakage current

Package Dimensions

Unit: mm



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The shapes and dimensions of the package vary, depending on the manufacturing plant. For details, contact the Toshiba sales representative.

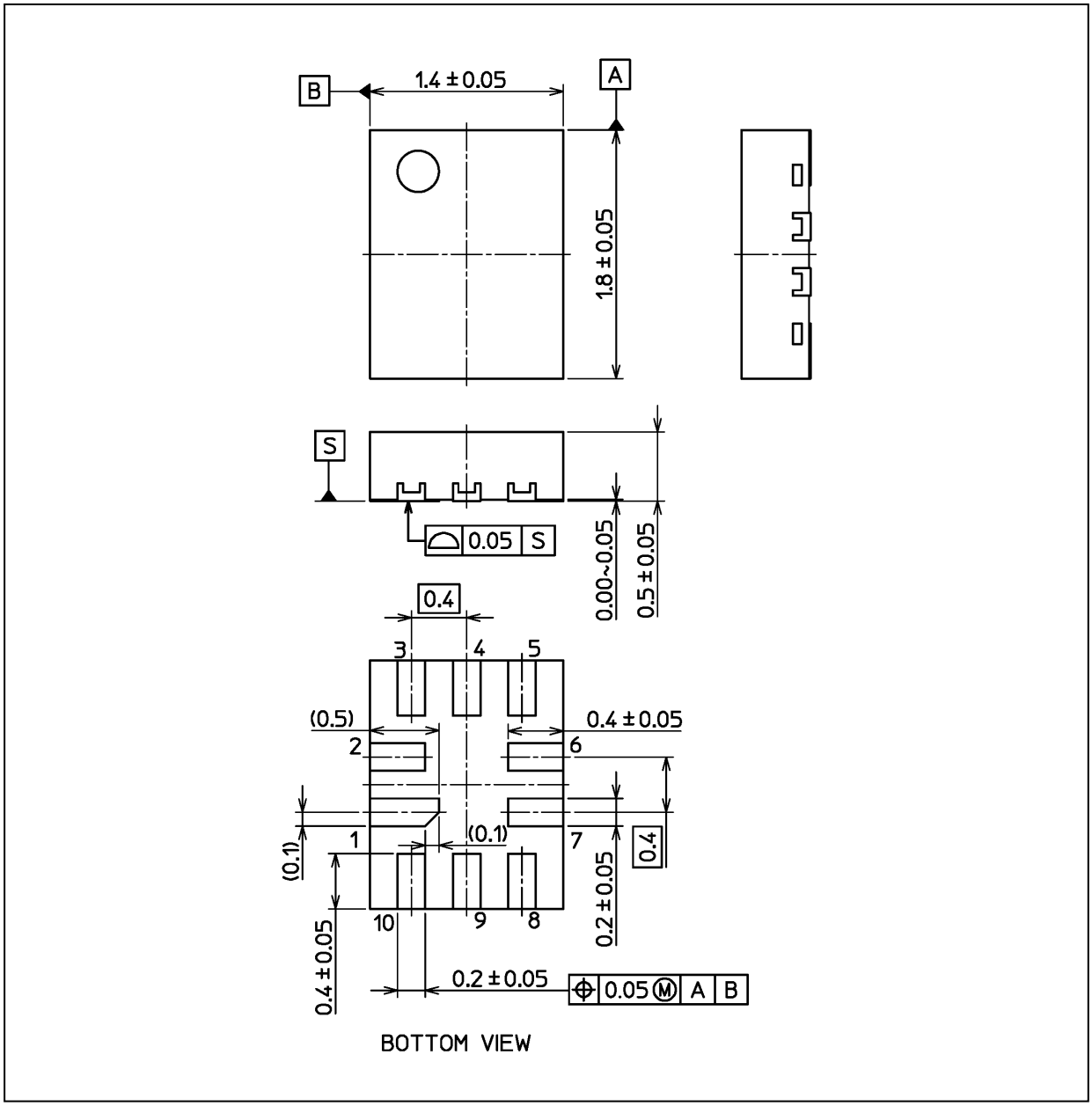
Weight: 4.0 mg (typ.)

Package Name(s)
Nickname: UQFN10B

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Package Dimensions

Unit: mm



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Weight: 3.5 mg (typ.)

Package Name(s)
Nickname: UQFN10

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